

MBN1200F33F

Silicon N-channel IGBT 3300V F version

FEATURES

- * Soft switching behavior, low switching loss & low conduction loss :
Soft low-injection punch-through
Advanced Trench High conductivity IGBT.
- * Low driving power due to low input capacitance with trench MOS gate.
- * Low noise recovery: Ultra soft fast recovery diode.
- * High Current rate Package.
- * Low Rth(j-c) & low stray inductance.
- * RoHS
- * High thermal fatigue durability:
($\Delta T_c=70K$, $N>30,000$ cycles)

ABSOLUTE MAXIMUM RATINGS ($T_c=25^\circ\text{C}$)

Item	Symbol	Unit	MBN1200F33F
Collector Emitter Voltage	V_{CES}	V	3,300
Gate Emitter Voltage	V_{GES}	V	± 20
Collector Current	DC	I_C	1200
	1ms	I_{CRM}	2,400
Forward Current	DC	I_F	1200
	1ms	I_{FRM}	2,400
Junction Temperature	T_j	$^\circ\text{C}$	-50 ~ +150
Storage Temperature	T_{stg}	$^\circ\text{C}$	-55 ~ +150
Isolation Voltage	V_{ISO}	V_{RMS}	6,000(AC 1 minute)
Screw Torque	Terminals (M4/M8)	-	2/15 (1)
	Mounting (M6)	-	6 (2)

Notes: (1) Recommended Value $1.8 \pm 0.2/15^{+0}_{-3} \text{N}\cdot\text{m}$ (2) Recommended Value $5.5 \pm 0.5 \text{N}\cdot\text{m}$

ELECTRICAL CHARACTERISTICS

Item	Symbol	Unit	Min.	Typ.	Max.	Test Conditions
Collector Emitter Cut-Off Current	I_{CES}	mA	-	-	0.4	$V_{CE}=3,300\text{V}$, $V_{GE}=0\text{V}$, $T_j=25^\circ\text{C}$
			-	25	65	$V_{CE}=3,300\text{V}$, $V_{GE}=0\text{V}$, $T_j=150^\circ\text{C}$
Gate Emitter Leakage Current	I_{GES}	nA	-500	-	+500	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_j=25^\circ\text{C}$
Collector Emitter Saturation Voltage	V_{CESat}	V	2.5	2.85	3.5	$I_C=1200\text{A}$, $V_{GE}=15\text{V}$, $T_j=150^\circ\text{C}$
Gate Emitter Threshold Voltage	$V_{GE(th)}$	V	5.5	6.5	7.5	$V_{CE}=10\text{V}$, $I_C=1200\text{mA}$, $T_j=25^\circ\text{C}$
Input Capacitance	C_{ies}	nF	-	88	-	$V_{CE}=10\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$, $T_j=25^\circ\text{C}$
Internal Gate Resistance	r_g	Ω	-	1.9	-	$V_{CE}=10\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$, $T_j=25^\circ\text{C}$
Switching Times	Rise Time	t_r	0.1	0.2	0.3	$V_{CC}=1,800\text{V}$, $I_C=1200\text{A}$
	Turn On Time	t_{on}	0.8	1.2	1.6	$L_s=100\text{nH}$
	Fall Time	t_f	1.0	1.8	2.6	$R_G(\text{on})=6.8\Omega$, $R_G(\text{off})=8.2\Omega$ (3)
	Turn Off Time	t_{off}	2.7	4.5	5.9	$V_{GE}=\pm 15\text{V}$, $T_j=150^\circ\text{C}$
Peak Forward Voltage Drop	V_F	V	2.2	2.6	2.9	$I_F=1200\text{A}$, $V_{GE}=0\text{V}$, $T_j=150^\circ\text{C}$
Reverse Recovery Time	t_{rr}	μs	0.2	0.7	1.1	$V_{CC}=1,800\text{V}$, $I_F=1200\text{A}$, $L_s=100\text{nH}$ $T_j=150^\circ\text{C}$
Turn On Loss	E_{on}	J/P	-	2.6	3.4	$V_{CC}=1,800\text{V}$, $I_C=1200\text{A}$, $L_s=100\text{nH}$
Turn Off Loss	E_{off}	J/P	-	2.2	2.7	$R_G(\text{on})=6.8\Omega$, $R_G(\text{off})=8.2\Omega$ (3)
Reverse Recovery Loss	E_{rr}	J/P	-	1.7	2.2	$V_{GE}=\pm 15\text{V}$, $T_j=150^\circ\text{C}$
Stray inductance module	L_{SCE}	nH	-	10	-	
Thermal Impedance	IGBT	Rth(j-c)	-	-	0.010	Junction to case
	FWD	Rth(j-c)	-	-	0.017	
Contact Thermal Impedance	Rth(c-f)	K/W	-	0.008	-	Case to fin

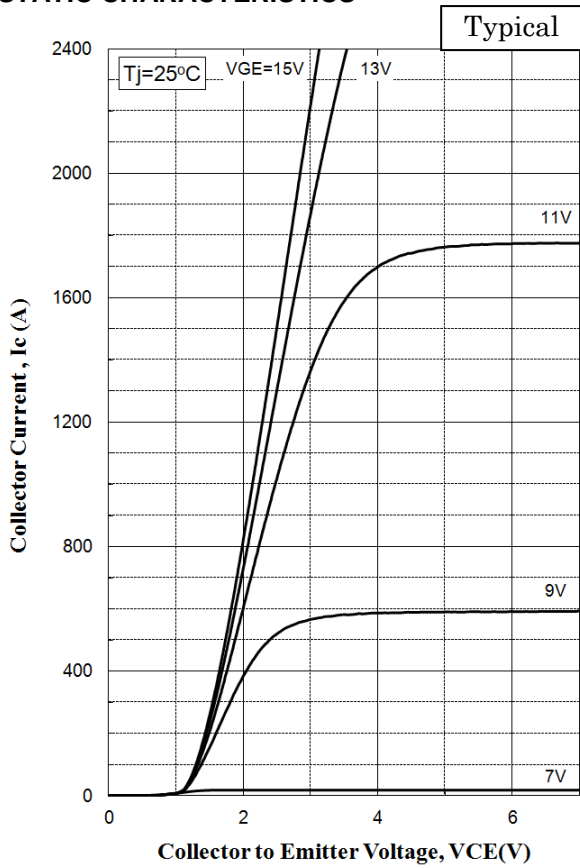
Notes: (3) R_G value is a test condition value for evaluation, not recommended value.

Please, determine the suitable R_G value by measuring switching behaviors.

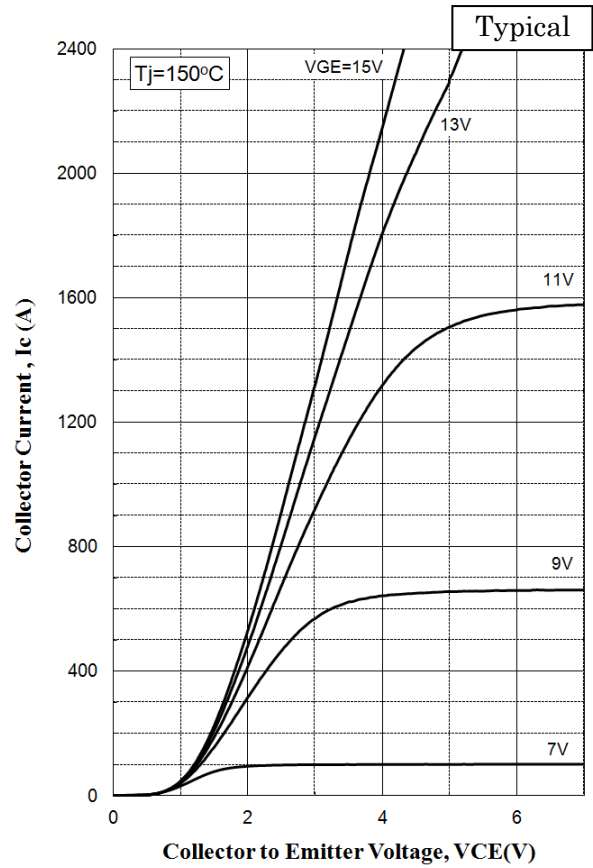
- * Please contact our representatives at order.
- * For improvement, specifications are subject to change without notice.
- * For actual application, please confirm this spec sheet is the newest revision.
- * ELECTRICAL CHARACTERISTIC values according to IEC 60747-2 IEC 60747-9

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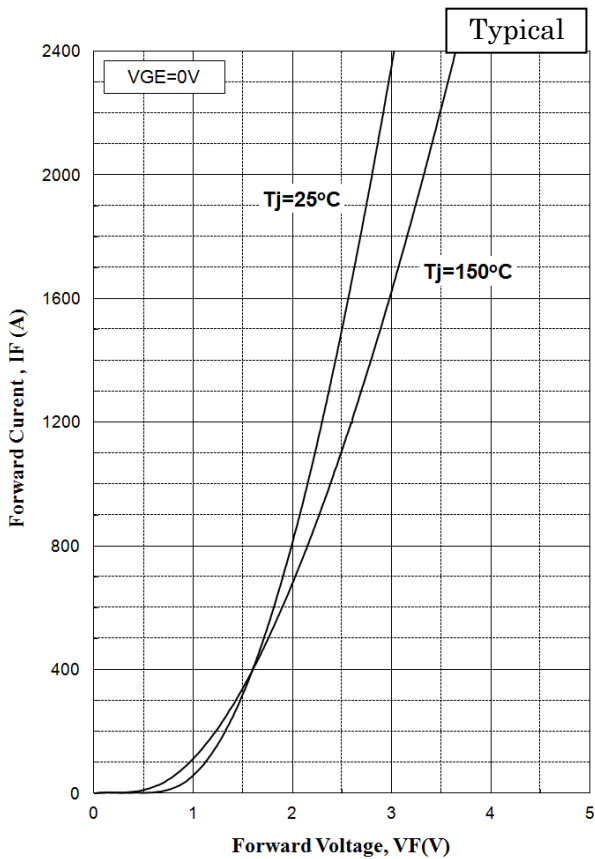
STATIC CHARACTERISTICS



Collector Current vs. Collector to Emitter Voltage



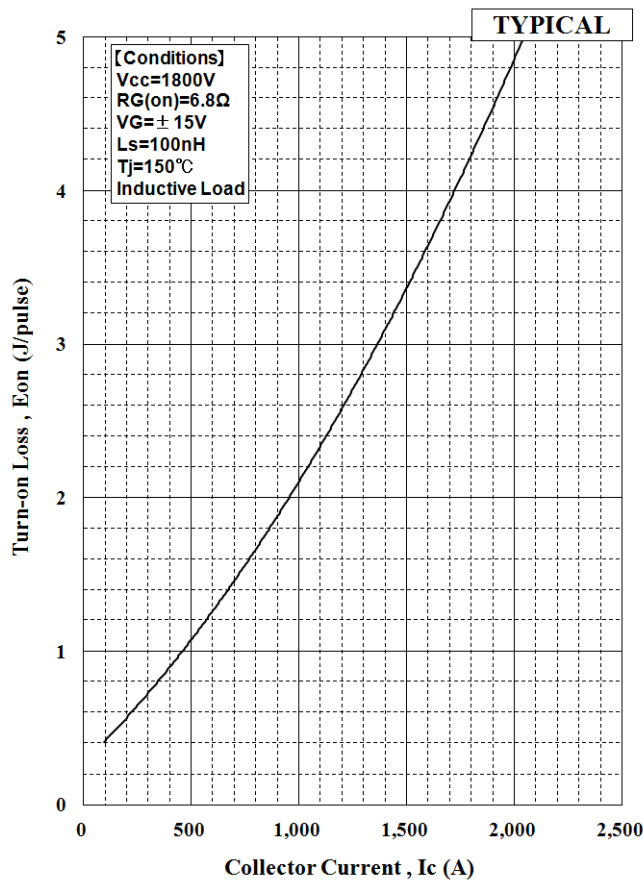
Collector Current vs. Collector to Emitter Voltage



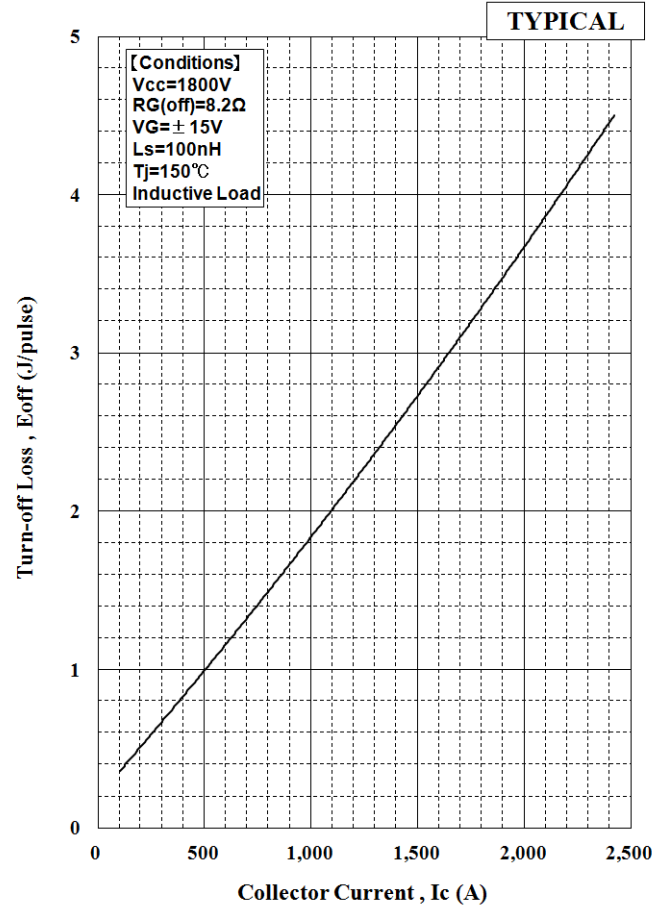
Forward Voltage of free-wheeling diode

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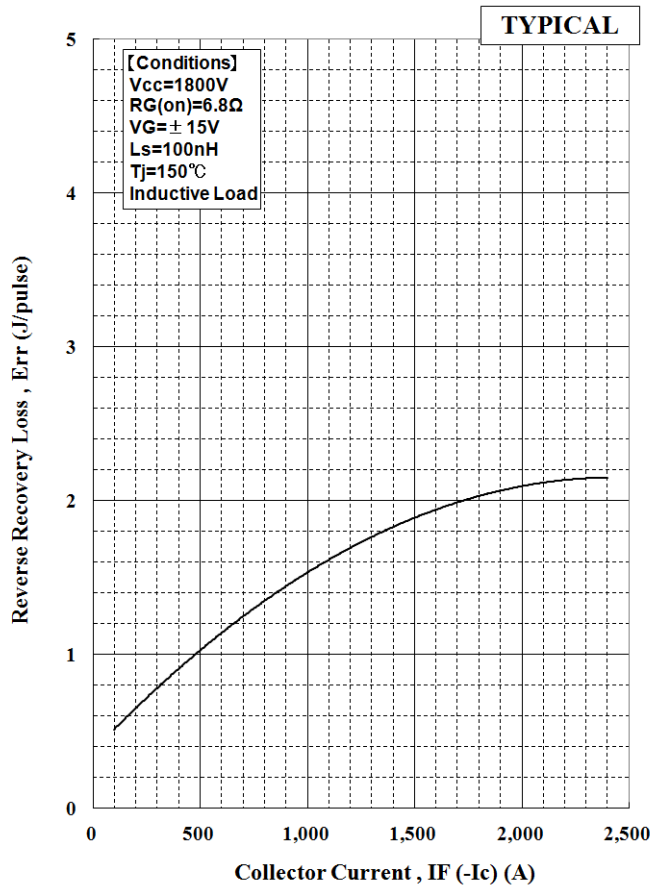
DYNAMIC CHARACTERISTICS



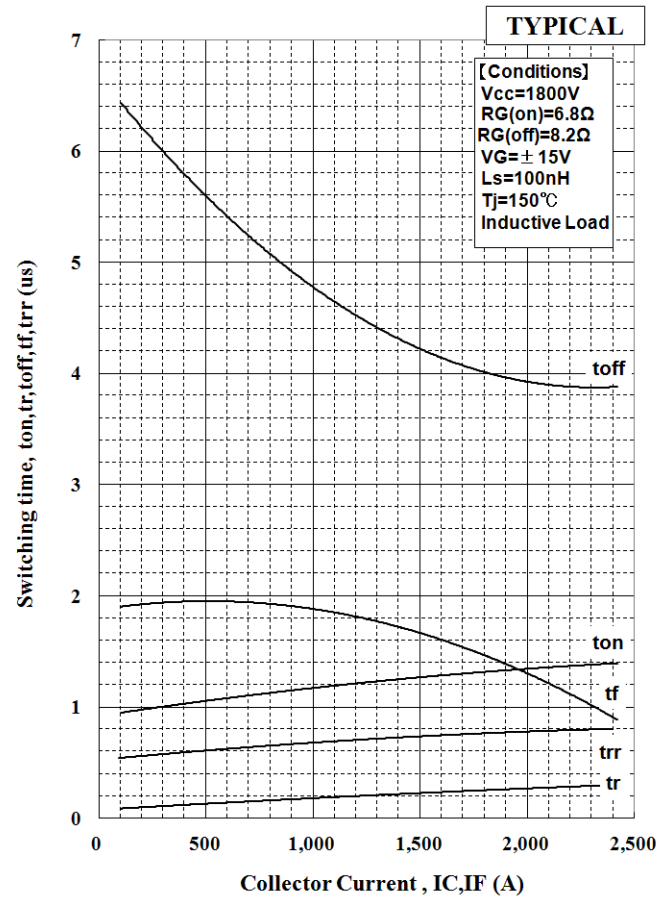
Turn-on Loss vs. Collector Current



Turn-off Loss vs. Collector Current

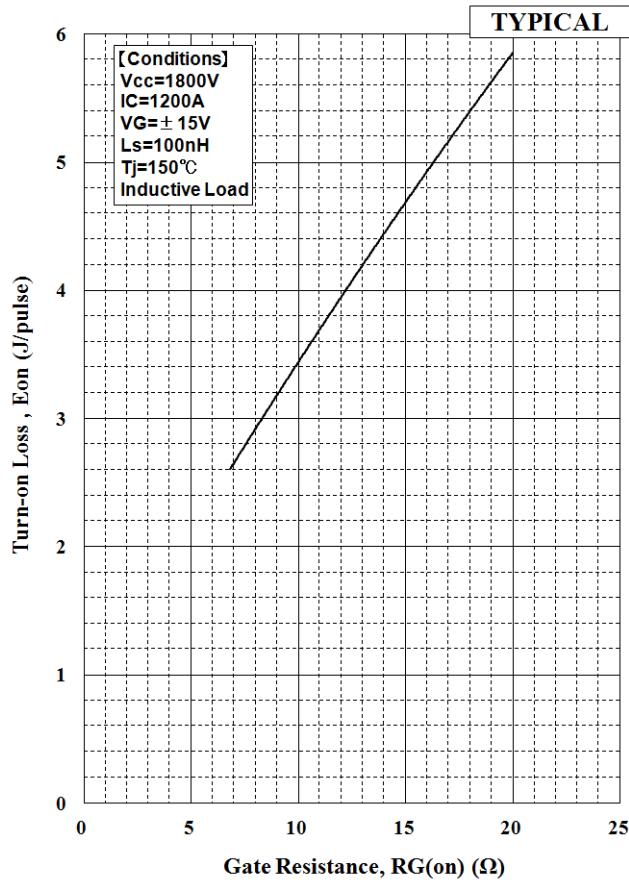


Recovery Loss vs. Collector Current

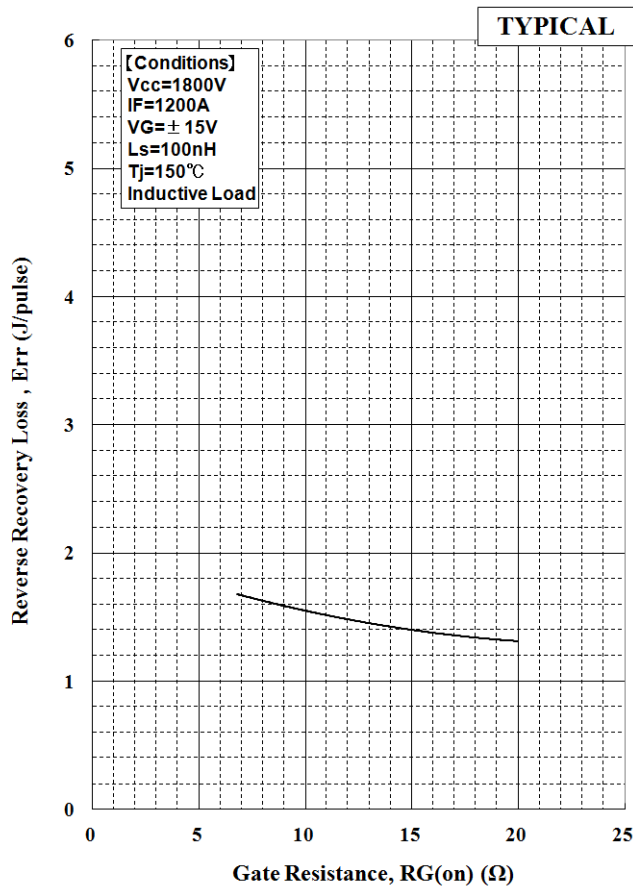
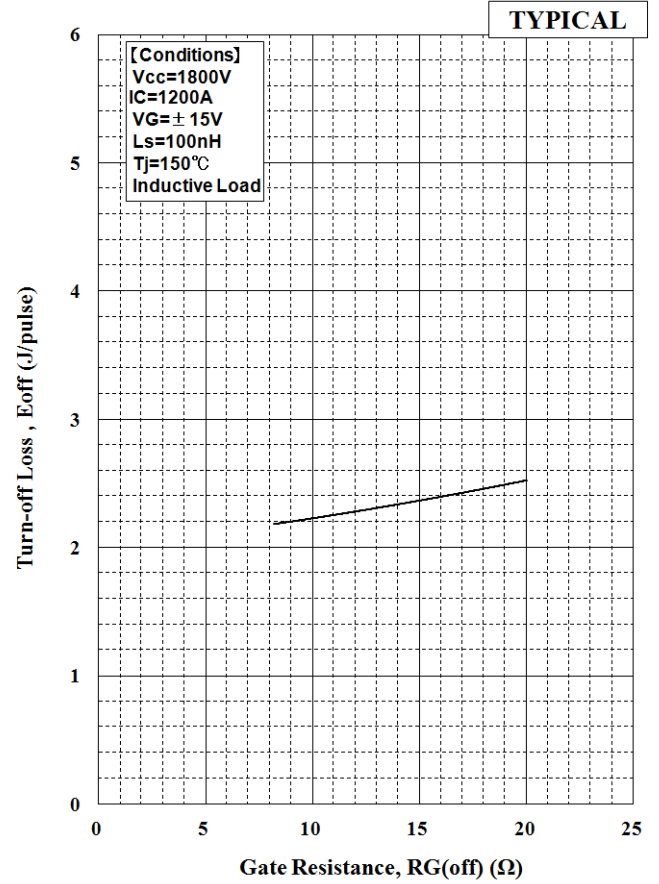


Switching time vs. Collector Current

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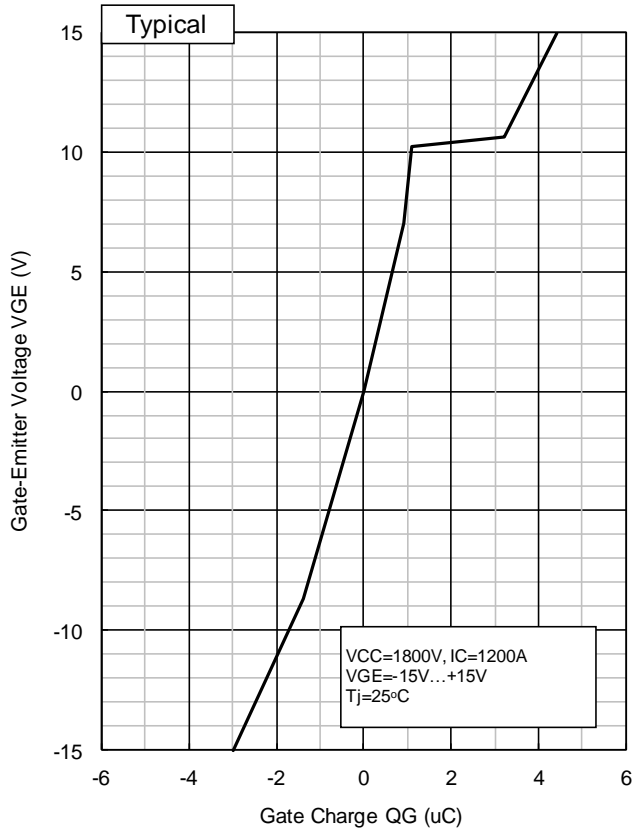
Turn-on Loss vs. Gate Resistance



Recovery Loss vs. Gate Resistance

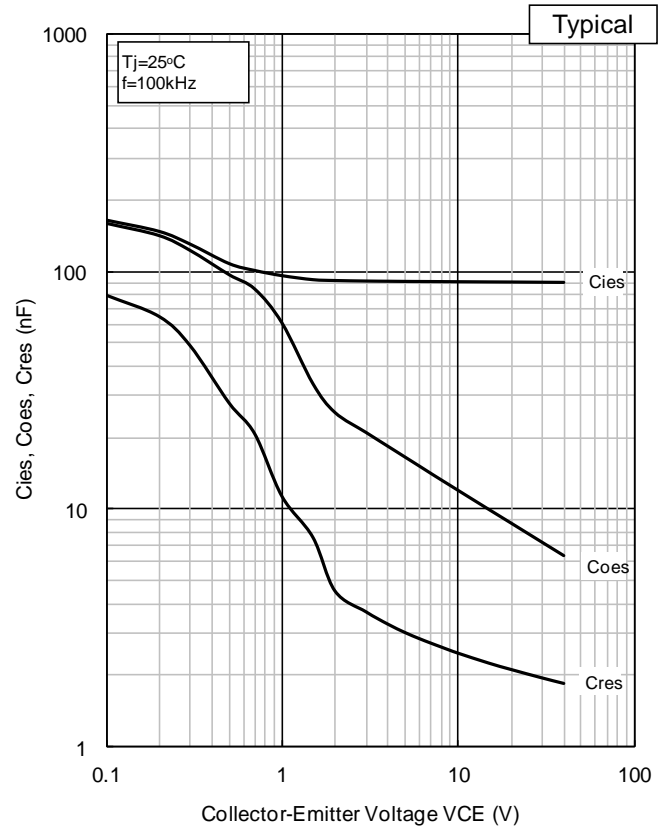
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QG-VG CURVE



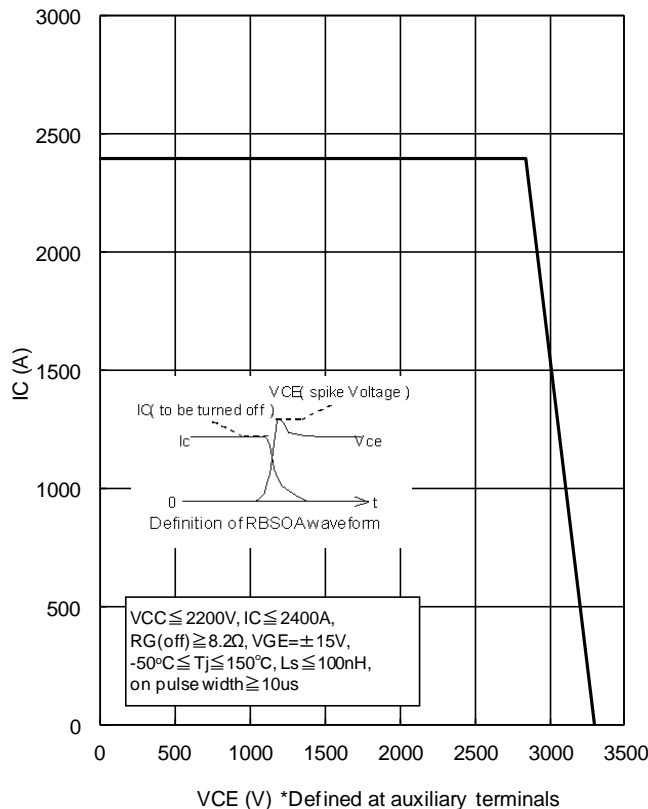
QG - VGE

Cies, Coes, Cres Curve

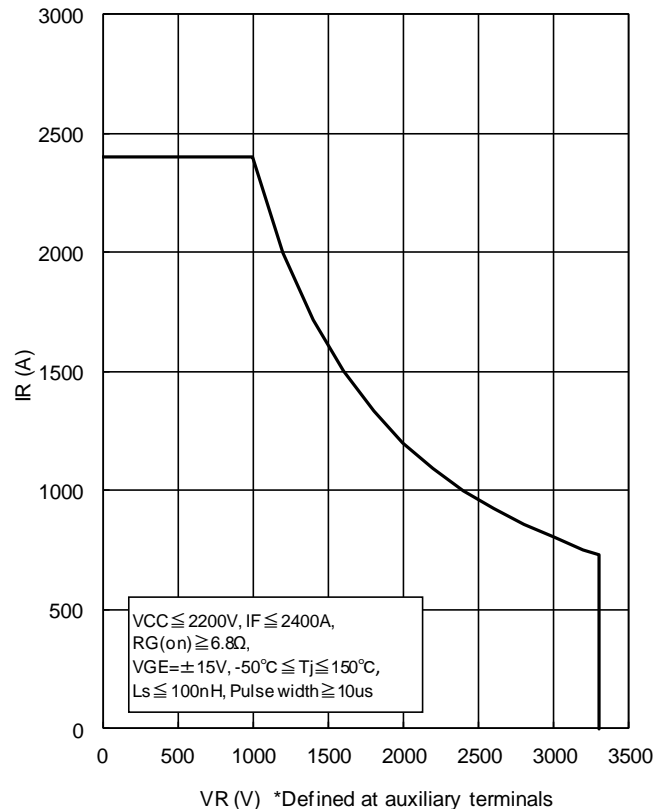


Cies, Coes, Cres - VCE

Safe Operating Area



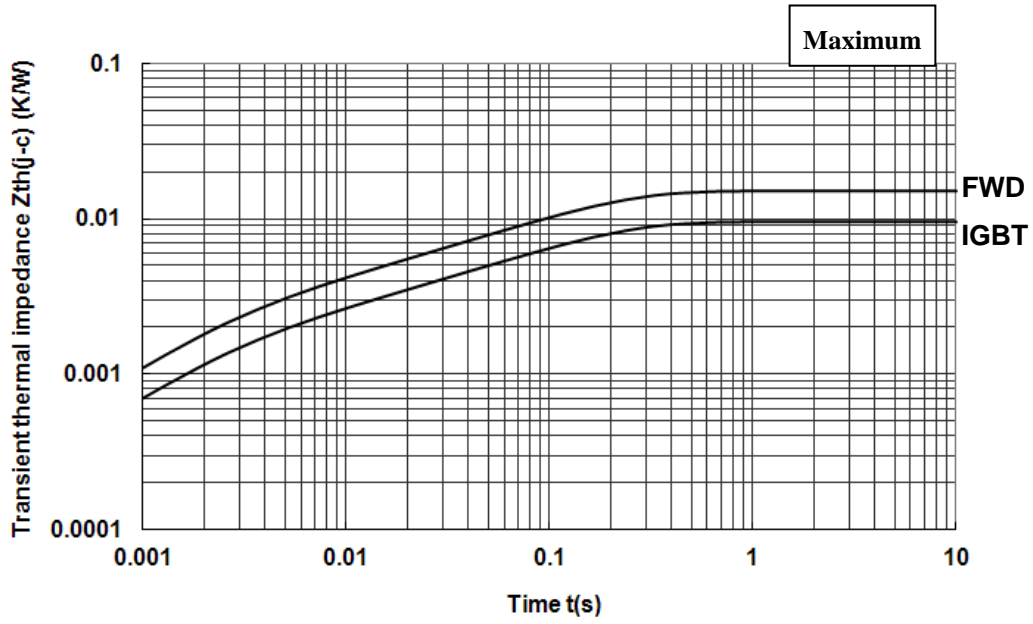
RBSOA



RecSOA

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TRANSIENT THERMAL IMPEDANCE



Transient Thermal Impedance Curve

Curve approximation model

$$Z_{th} = \sum r_{th}[n] * (1 - \exp(-t/r_{th}[n]))$$

n	1	2	3	4	Unit
$\tau_{th}[n]$	1.28E-01	1.56E-02	2.69E-03	3.16E-04	sec
$r_{th}[n,IGBT]$	6.47E-03	2.18E-03	1.28E-03	7.04E-05	K/W
$r_{th}[n,Diode]$	1.10E-02	3.78E-03	2.13E-03	1.24E-04	K/W

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OUTLINE DRAWINGS

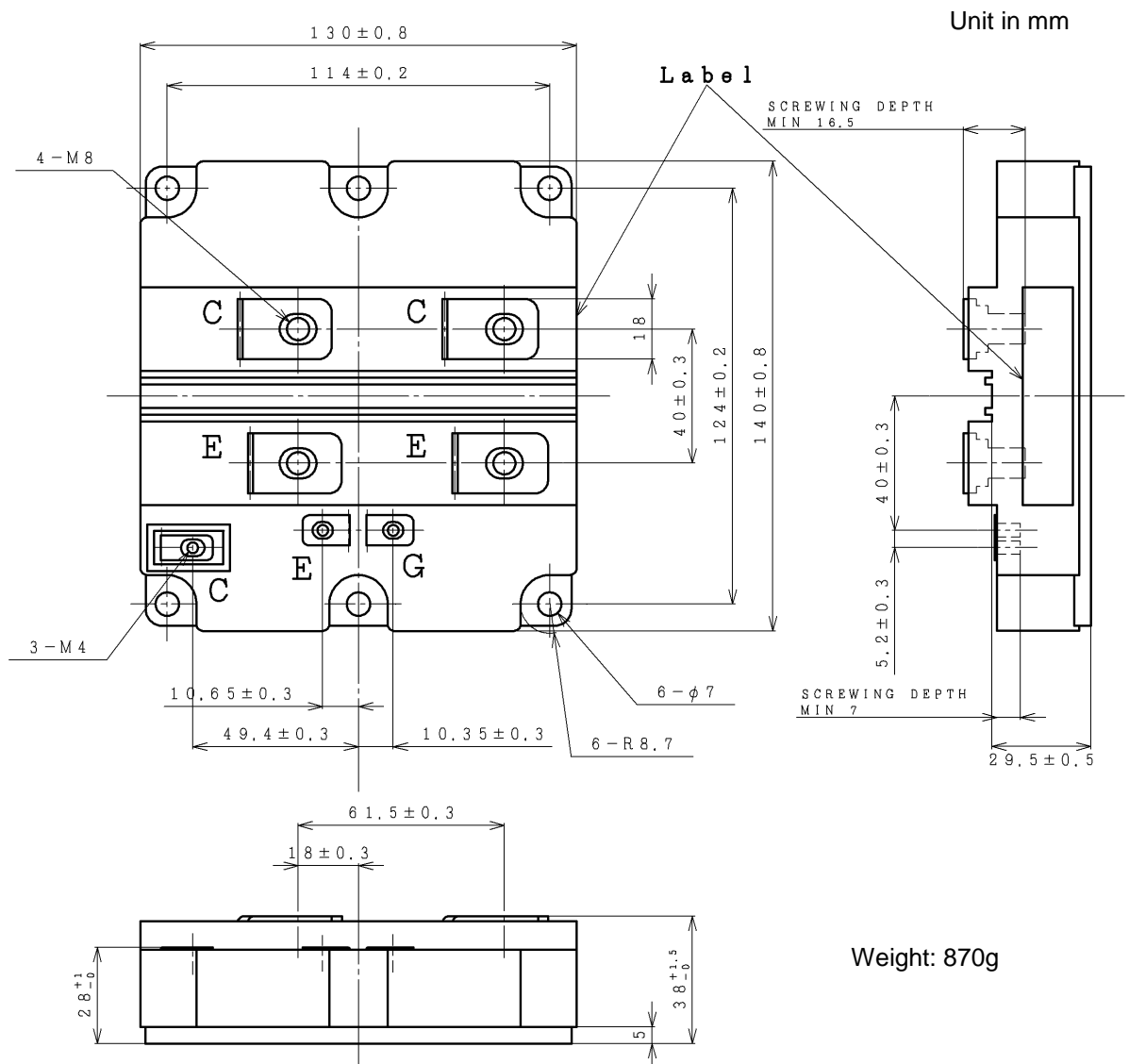


Fig.1 Outline Drawings

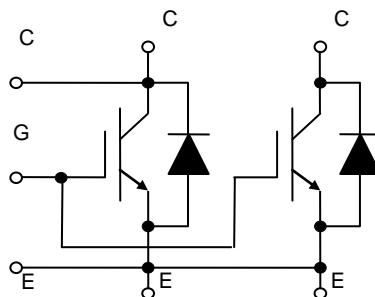


Fig.2 Circuit diagram

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HITACHI POWER SEMICONDUCTORS

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